

HOCH XPS EXTRUDED POLYSTYRENE

HOCH XPS (eXtruded PolyStyrene foam) insulation boards are a homogeneous and cellular insulation material. It is formed during the extrusion of polystyrene, at a well-defined temperature and pressure, which results in a foam characterized by small, irregular, closely adherent cells. It guarantees high mechanical strength, resistance to water and adverse weather conditions, as well as excellent thermal insulation performance. High compressive strength, ease of installation, light weight and the variety of thicknesses available, make HOCH XPS insulation boards an excellent insulation material with versatile use in construction. HOCH XPS extruded polystyrene boards have been manufactured in accordance with EN 13164:2012 + A1: 2015. This product does not contain flame retardants.

OVERALL DIMENSIONS OF THE BOARDS

Edge finishing	Length [mm]	Width [mm]
I	1250	600
L	1265	615
PW	1265	615

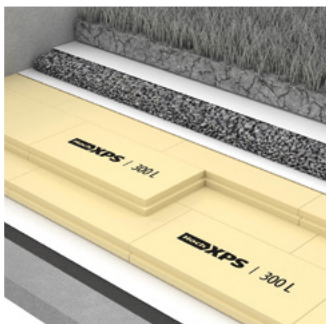
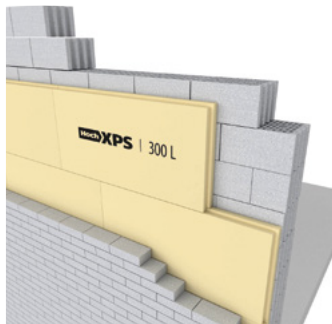
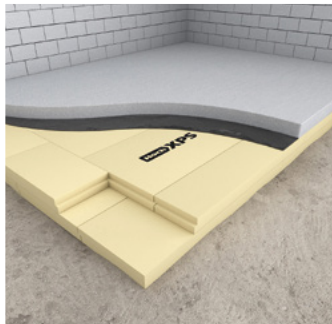
APPLICATION:

Thermal insulation in construction:

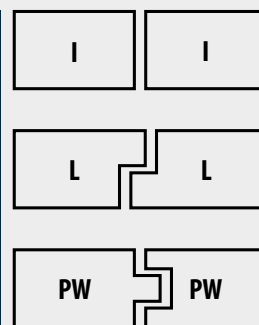
- thermal insulation of foundations and basement walls,
- thermal insulation of floors and floorings,
- thermal insulation of building façades,
- thermal insulation of interior walls,
- thermal insulation of pitched roofs and inverted roofs (flat roofs),
- thermal insulation of terraces and balconies.

ADVANTAGES OF XPS BOARDS:

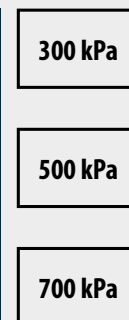
- very low thermal conductivity coefficient,
- closed-cell structure, resulting in a very low absorbability,
- high compressive strength,
- ease of board installation,
- full recycling (no waste),
- cellular structure, filled with air, maintains thermal insulation performance stable over time,
- Polish product.



EDGE FINISHING:



COMPRESSIVE STRENGTH:



TECHNICAL PARAMETERS	Symbol / Unit	THICKNESS															
		XPS200		XPS300						XPS500				XPS700			
		20	30	40	50	60	80	100	120	150	50	80	100	120	50	80	100
Thermal conductivity coefficient	λ_b [W/mK]	≤ 0.034	≤ 0.032	≤ 0.032	≤ 0.032	≤ 0.032	≤ 0.034	≤ 0.034	≤ 0.036	≤ 0.036	≤ 0.034	≤ 0.034	≤ 0.036	≤ 0.036	≤ 0.034	≤ 0.034	≤ 0.036

INSTALLATION

Solvent adhesives in contact with XPS HOCH boards cause undesirable effects; destruction of XPS boards occurs. Before installation, check whether the adhesive can be used for polystyrene foam. Boards exposed to UV radiation may degrade; it is imperative to cover them with bright UV-impermeable material. If you glue the boards, the surface should be rough in order to improve the board–glue bonding. Application of the product at low temperatures requires a sufficiently large space between boards to maintain proper expansion.

PACKAGING

HOCH XPS boards are packed in a package wrapped in plastic and then stored on a pallet.

PACKAGE				
XPS board thickness [mm]	Number of boards per package [pcs]	Area of boards per package [m²]	Volume of boards per package [m³]	Package height [m]
20	20	15	0.3	0.4
30	14	10.5	0.315	0.42
40	10	7.5	0.3	0.4
50	8	6	0.3	0.4
60	7	5.25	0.315	0.42
80	5	3.75	0.3	0.4
100	4	3	0.3	0.4
120	4	3	0.36	0.48
140	3	2.25	0.315	0.42
150	3	2.25	0.3375	0.45
160	3	2.25	0.36	0.48
180	2	1.5	0.27	0.36
200	2	1.5	0.3	0.40

PALETTE					
XPS board thickness [mm]	Number of packages per pallet [pcs]	Number of boards per pallet [pcs]	Area of boards per pallet [m²]	Volume of boards per pallet [m³]	Height with a sleeper [m]
20	12	240	180	3.6	2.48
30	12	168	126	3.78	2.60
40	12	120	90	3.6	2.48
50	12	96	72	3.6	2.48
60	12	84	63	3.78	2.60
80	12	60	45	3.6	2.48
100	12	48	36	3.6	2.48
120	10	40	30	3.6	2.48
140	12	36	27	3.78	2.6
150	10	30	22.5	3.375	2.33
160	10	30	22.5	3.6	2.48
180	14	28	21	3.78	2.6
200	12	24	18	3.6	2.48

MANUFACTURER

HOCH Sp. z o.o. Sp. k.
ul. Jana Pawła II 56
83-422 Nowy Barkoczyn, Poland

T: +48 535 937 937
E: biuro@hoch.com.pl
www.hoch.com.pl

NIP (Tax ID) 591-169-90-65
REGON 365146413
KRS 0000632064



EXCELLENT
THERMAL
INSULATION



WATERPROOFNESS



VERY HIGH
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STRENGTH



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RESISTANCE

